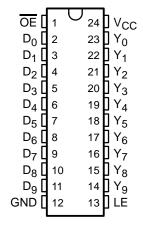
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- **Function, Pinout, and Drive Compatible** With FCT, F, and AM29841 Logic
- Reduced V<sub>OH</sub> (Typically = 3.3 V) Versions of **Equivalent FCT Functions**
- **Edge-Rate Control Circuitry for Significantly Improved Noise** Characteristics
- Ioff Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- **ESD Protection Exceeds JESD 22** 
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- **Fully Compatible With TTL Input and Output Logic Levels**
- **High-Speed Parallel Latches**
- **Buffered Common Latch-Enable Input**
- **3-State Outputs**
- CY54FCT841T
  - 32-mA Output Sink Current
  - 12-mA Output Source Current
- CY74FCT841T
  - 64-mA Output Sink Current
  - 32-mA Output Source Current

#### CY54FCT841T . . . D PACKAGE CY74FCT841T . . . P. Q. OR SO PACKAGE (TOP VIEW)



## description

The 'FCT841T bus-interface latches are designed to eliminate additional packages required to buffer existing latches and provide additional data width for wider address/data paths or buses carrying parity. The 'FCT841T devices are buffered 10-bit-wide versions of the FCT373 function.

The 'FCT841T devices' high-performance interface is designed for high-capacitance-load drive capability, while providing low-capacitance bus loading at both inputs and outputs. Outputs are designed for low-capacitance bus loading in the high-impedance state.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### PIN DESCRIPTION

NAME	I/O	DESCRIPTION
D	I	Latch data inputs
LE	ı	Latch-enable input. The latches are transparent when LE is high. Input data is latched on the high-to-low transition.
Υ	0	3-state latch outputs
ŌĒ	ı	Output-enable control. When OE is low, the outputs are enabled. When OE is high, the outputs are in the high-impedance (off) state.



testing of all parameters.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of



### **ORDERING INFORMATION**

TA	PACI	(AGE <sup>†</sup>	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP - Q	Tape and reel	5.5	CY74FCT841CTQCT	FCT841C
	SOIC - SO	Tube	5.5	CY74FCT841CTSOC	FCT841C
–40°C to 85°C	3010 - 30	Tape and reel	5.5	CY74FCT841CTSOCT	FC1041C
-40 C to 65 C	DIP – P	Tube	6.5	CY74FCT841BTPC	CY74FCT841BTPC
	SOIC - SO	Tube	9	CY74FCT841ATSOC	FCT841A
	3010 - 30	Tape and reel	9	CY74FCT841ATSOCT	FC1041A
–55°C to 125°C	CDIP – D	Tube	10	CY54FCT841ATDMB	

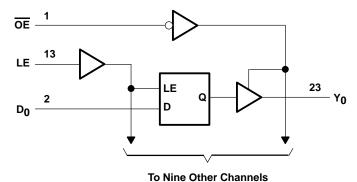
<sup>†</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

IN	INPUTS		INTER OUT	RNAL PUTS	FUNCTION
Ē	LE	D	0	Υ	
1	Х	Х	Х	Z	
ł	Н	L	L	Z	Z
1	Н	Н	Н	Z	
ł	L	Χ	NC	Z	Latched (Z)
-	Н	L	L	L	Transparent
-	Н	Н	Н	Н	Transparent
-	L	Х	NC	NC	Latched

H = High logic level, L = Low logic level, X = Don't care, NC = No change, Z = High-impedance state

## logic diagram (positive logic)



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	-0.5	V to 7 V
DC input voltage range	-0.5	V to 7 V
DC output voltage range	-0.5	$V$ to $7\ V$
DC output current (maximum sink current/pin)		120 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 1): P package		67°C/W
(see Note 2): Q package		61°C/W
(see Note 2): SO package		46°C/W
Ambient temperature range with power applied, T <sub>A</sub> –	65°C t	o 135°C
Storage temperature range, T <sub>stq</sub> –	65°C t	o 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

		CY54FCT841T			CY7	74FCT84	1T	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-12			-32	mA
loL	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.



NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-3.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

## **CY54FCT841T, CY74FCT841T 10-BIT LATCHES** WITH 3-STATE OUTPUTS

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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEST CONDITION	NG.	CY	54FCT84	I1T	CY	74FCT84	1T	LINUT
PARAMETER		TEST CONDITION	NS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT
Viva	$V_{CC} = 4.5 \text{ V},$	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2				٧
VIK	$V_{CC} = 4.75 \text{ V},$	I <sub>IN</sub> = -18 mA						-0.7	-1.2	V
	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -12 mA		2.4	3.3					
Voн	V 475 V	I <sub>OH</sub> = -32 mA					2			V
	V <sub>CC</sub> = 4.75 V	I <sub>OH</sub> = -15 mA					2.4	3.3		
	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 32 mA			0.3	0.55				
VOL	V <sub>CC</sub> = 4.75 V,	I <sub>OL</sub> = 64 mA						0.3	0.55	V
V <sub>hys</sub>	All inputs				0.2			0.2		V
	$V_{CC} = 5.5 \text{ V},$	V <sub>IN</sub> = V <sub>CC</sub>				5				
l 1	V <sub>CC</sub> = 5.25 V,	VIN = VCC							5	μΑ
	$V_{CC} = 5.5 \text{ V},$	V <sub>IN</sub> = 2.7 V				±1				
ΊΗ	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 2.7 V							±1	μΑ
	$V_{CC} = 5.5 \text{ V},$	V <sub>IN</sub> = 0.5 V				±1				
l⊓l⊓	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 0.5 V							±1	μΑ
	$V_{CC} = 5.5 \text{ V},$	V <sub>OUT</sub> = 2.7 V			-	10				
lozh	$V_{CC} = 5.25 \text{ V},$	V <sub>OUT</sub> = 2.7 V						-	10	μΑ
	V <sub>CC</sub> = 5.5 V,	V <sub>OUT</sub> = 0.5 V				-10				
lozL	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 0.5 V							-10	μΑ
. +	$V_{CC} = 5.5 \text{ V},$	V <sub>OUT</sub> = 0 V		-60	-120	-225				^
los <sup>‡</sup>	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 0 V					-60	-120	-225	mA
l <sub>off</sub>	$V_{CC} = 0 V$ ,	V <sub>OUT</sub> = 4.5 V				±1			±1	μΑ
	$V_{CC} = 5.5 \text{ V},$	V <sub>IN</sub> ≤ 0.2 V,	V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V		0.1	0.2				4
Icc	V <sub>CC</sub> = 5.25 V,	$V_{IN} \le 0.2 V$ ,	$V_{IN} \ge V_{CC} - 0.2 V$					0.1	0.2	mA
Aloo	$V_{CC} = 5.5 \text{ V}, V_{IN} =$	= 3.4 V <sup>§</sup> , f <sub>1</sub> = 0, Ou	tputs open		0.5	2				mA
ΔICC	$V_{CC} = 5.25 \text{ V}, V_{IN}$	$= 3.4 \text{ V}$ , $f_1 = 0$ , O	utputs open					0.5	2	IIIA
	$V_{CC} = 5.5 \text{ V}, One i$		0% duty cycle,		0.06	0.12				
_ VINI ≤ 0.2 V OF		ts open, $\overline{OE}$ = GND, LE = V <sub>CC</sub> , 0.2 V or V <sub>IN</sub> $\geq$ V <sub>CC</sub> $-$ 0.2 V			0.00	0.12			m.	mA/
ICCD¶	V <sub>CC</sub> = 5.25 V, <u>One</u>	input switching at	50% duty cycle,		•			-		MHz
	Outputs open, OE : V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub>							0.06	0.12	
± ==	VIN S 0.2 V 01 VIN									

<sup>†</sup> Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>‡</sup> Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

 $<sup>\</sup>S$  Per TTL-driven input (V<sub>IN</sub> = 3.4 V); all other inputs at V<sub>CC</sub> or GND

This parameter is derived for use in total power-supply calculations.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETER		TEST CONDITION	ie.	CY	54FCT84	11T	CY	74FCT84	1T	LINIT
PARAMETER		TEST CONDITION		MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT
	V <sub>CC</sub> = 5.5 V,	One bit switching at f <sub>1</sub> = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	Outputs open,	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1	2.4				
	OE = GND, LE = V <sub>CC</sub>	10 bits switching at f <sub>1</sub> = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		1	3.2				
l <sub>C</sub> #		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		4.1	13.2				mA
ıC"	V <sub>CC</sub> = 5.25 V,	One bit switching at f <sub>1</sub> = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	Outputs open,	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1	2.4	
	OE = GND, LE = V <sub>CC</sub>	10 bits switching at f <sub>1</sub> = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					1	3.2	
		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					4.1	13.2	
C <sub>i</sub>					5	10		5	10	pF
Co		•			9	12		9	12	pF

† Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . #  $I_{CC} = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$ 

Where:

= Total supply current IC

I<sub>CC</sub> = Power-supply current with CMOS input levels

 $\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4 \text{ V}$ )

D<sub>H</sub> = Duty cycle for TTL inputs high N<sub>T</sub> = Number of TTL inputs at D<sub>H</sub>

ICCD = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero

= Input signal frequency

= Number of inputs changing at f<sub>1</sub>

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I<sub>CC</sub> formula.

## timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			CY54FCT841AT		CY74FCT841AT		CY74FCT841BT		CY74FCT841CT	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t <sub>W</sub>	Pulse duration, LE high	5		4		4		4		ns
t <sub>su</sub>	Setup time, data before LE↑	2.5		2.5		2.5		2.5		ns
th	Hold time, data after LE↑	3		2.5		2.5		2.5		ns



## CY54FCT841T, CY74FCT841T 10-BIT LATCHES WITH 3-STATE OUTPUTS

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# switching characteristics over operating free-air temperature range (see Figure 1)

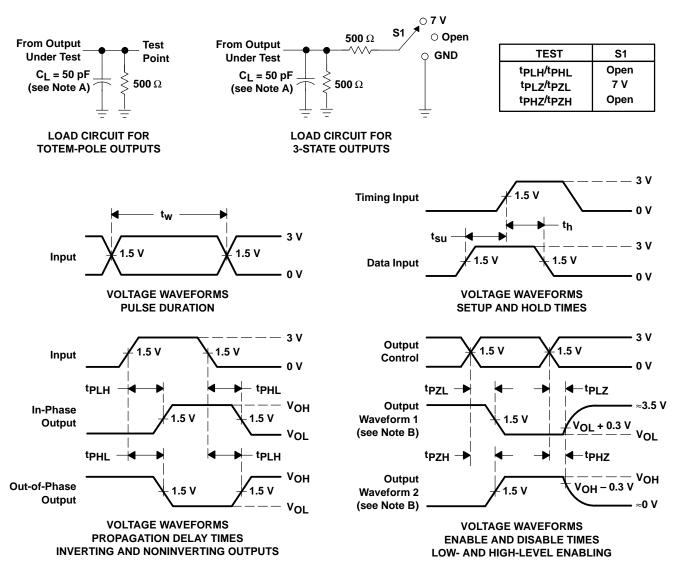
DARAMETER	FROM	то	TEST LOAD	CY54FCT	841AT	CY74FCT	841AT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST LOAD	MIN	MAX	MIN	MAX	UNII
t <sub>PLH</sub>	D	Υ	C <sub>L</sub> = 50 pF,	1.5	10	1.5	9	ns
<sup>t</sup> PHL	D	I	$R_L = 500 \Omega$	1.5	10	1.5	9	115
<sup>t</sup> PLH	D	Y	C <sub>L</sub> = 300 pF,	1.5	15	1.5	13	ns
<sup>t</sup> PHL	D	T	$R_L = 500 Ω$	1.5	15	1.5	13	115
<sup>t</sup> PLH	LE	Y	C <sub>L</sub> = 50 pF,	1.5	13	1.5	12	ns
<sup>t</sup> PHL	LE	I	$R_L = 500 \Omega$	1.5	13	1.5	12	115
<sup>t</sup> PLH	LE	Y	C <sub>L</sub> = 300 pF,	1.5	20	1.5	16	ns
<sup>t</sup> PHL	LL	I	$R_L = 500 \Omega$	1.5	20	1.5	16	115
<sup>t</sup> PZH	<u>OE</u>	Y	C <sub>L</sub> = 50 pF,	1.5	13	1.5	11.5	ns
<sup>t</sup> PZL	OE	I	$R_L = 500 \Omega$	1.5	13	1.5	11.5	115
<sup>t</sup> PZH	ŌĒ	Y	C <sub>L</sub> = 300 pF,	1.5	25	1.5	23	20
<sup>t</sup> PZL	OE	I	$R_L = 500 \Omega$	1.5	25	1.5	23	ns
<sup>t</sup> PHZ	ŌĒ	Y	C <sub>L</sub> = 5 pF,	1.5	9	1.5	7	ns
<sup>t</sup> PLZ	OE	I	$R_L = 500 \Omega$	1.5	9	1.5	7	115
<sup>t</sup> PHZ	ŌĒ	Υ	C <sub>L</sub> = 50 pF,	1.5	10	1.5	8	ns
<sup>t</sup> PLZ	OE	ı	$R_L = 500 \Omega$	1.5	10	1.5	8	119

## switching characteristics over operating free-air temperature range (see Figure 1)

DADAMETED	FROM	то	TEST LOAD	CY74FCT	841BT	CY74FCT	841CT	LINIT
PARAMETER	(INPUT)	(OUTPUT)	TEST LOAD	MIN	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	D	Y	C <sub>L</sub> = 50 pF,	1.5	6.5	1.5	5.5	
<sup>t</sup> PHL	]	'	$R_L = 500 \Omega$	1.5	6.5	1.5	5.5	ns
<sup>t</sup> PLH	D	Y	C <sub>L</sub> = 50 pF,	1.5	13	1.5	13	ns
<sup>t</sup> PHL	]	1	$R_L = 500 \Omega$	1.5	13	1.5	13	115
<sup>t</sup> PLH	LE	Y	C <sub>L</sub> = 50 pF,	1.5	8	1.5	6.4	ns
<sup>t</sup> PHL	] "	ī	$R_L = 500 \Omega$	1.5	8	1.5	6.4	115
<sup>t</sup> PLH	LE	Y	$C_L = 300 \text{ pF},$	1.5	15.5	1.5	15	ns
<sup>t</sup> PHL		ī	$R_L = 500 \Omega$	1.5	15.5	1.5	15	115
<sup>t</sup> PZH	<del>OE</del>	Y	C <sub>L</sub> = 50 pF,	1.5	8	1.5	6.5	ns
t <sub>PZL</sub>	] OE	Ť	$R_L = 500 \Omega$	1.5	8	1.5	6.5	ns
<sup>t</sup> PZH	<del>OE</del>	Y	C <sub>L</sub> = 300 pF,	1.5	14	1.5	12	
t <sub>PZL</sub>	OE OE	Ť	$R_L = 500 \Omega$	1.5	14	1.5	12	ns
<sup>t</sup> PHZ		Y	C <sub>L</sub> = 5 pF,	1.5	6	1.5	5.7	no
<sup>t</sup> PLZ	ŌĒ	T T	$R_L = 500 \Omega$	1.5	6	1.5	5.7	ns
<sup>t</sup> PHZ		Y	C <sub>L</sub> = 50 pF	1.5	7	1.5	6	no
t <sub>PLZ</sub>	<del>OE</del>	Ĭ Ť	$R_L = 500 \Omega$ ,	1.5	7	1.5	6	ns



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(.,	(=)			(8)	(4)	(5)		(0)
CY54FCT841ATDMB	Active	Production	CDIP (JT)   24	15   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CY54FCT841ATDM B
CY74FCT841ATSOC	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841A
CY74FCT841ATSOC.B	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841A
CY74FCT841ATSOCT	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841A
CY74FCT841ATSOCT.B	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841A
CY74FCT841CTQCT	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT841C
CY74FCT841CTQCT.B	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT841C
CY74FCT841CTSOC	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841C
CY74FCT841CTSOC.B	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841C
CY74FCT841CTSOCT	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841C
CY74FCT841CTSOCT.B	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841C

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



## PACKAGE OPTION ADDENDUM

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# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT841ATSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CY74FCT841CTQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT841CTSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CY74FCT841ATSOCT	SOIC	DW	24	2000	350.0	350.0	43.0	
CY74FCT841CTQCT	SSOP	DBQ	24	2500	353.0	353.0	32.0	
CY74FCT841CTSOCT	SOIC	DW	24	2000	350.0	350.0	43.0	

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CY74FCT841ATSOC	DW	SOIC	24	25	506.98	12.7	4826	6.6
CY74FCT841ATSOC.B	DW	SOIC	24	25	506.98	12.7	4826	6.6
CY74FCT841CTSOC	DW	SOIC	24	25	506.98	12.7	4826	6.6
CY74FCT841CTSOC.B	DW	SOIC	24	25	506.98	12.7	4826	6.6

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